

Product Summary

$V_{(BR)DSS}$	$R_{DS(on)TYP}$	I_D
150V	5.2mΩ@10V	185A



合肥矽普半导体

Siliup Semiconductor Technology Co., Ltd

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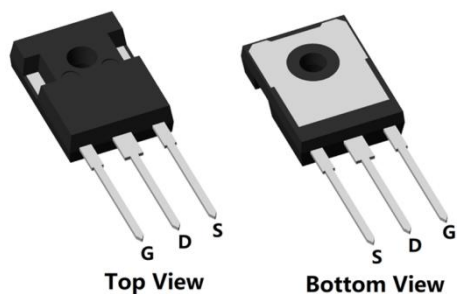
Feature

- Fast Switching
- Low Gate Charge and Rdson
- Advanced Split Gate Trench Technology
- 100% Single Pulse avalanche energy Test

Applications

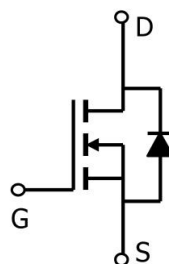
- Power switching application
- DC-DC Converter
- Power Management

Package

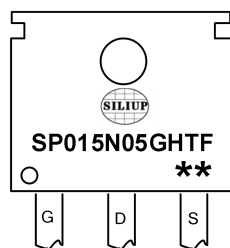


TO-247(1:G 2:D 3:S)

Circuit diagram



Marking



SP015N05GHTF

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:Product code

:Week code

Order Information

Device	Package	Unit/Tube
SP015N05GHTF	TO-247	30

Absolute maximum ratings (Ta=25°C, unless otherwise noted)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DS}	150	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current (Tc=25°C)	I_D	185	A
Continuous Drain Current (Tc=100°C)	I_D	125	A
Pulsed Drain Current	I_{DM}	740	A
Single Pulse Avalanche Energy ¹	E_{AS}	1225	mJ
Power Dissipation (Tc=25°C)	P_D	335	W
Thermal Resistance Junction-to-Case	$R_{\theta JC}$	0.37	°C/W
Storage Temperature Range	T_{STG}	-55 to 150	°C
Operating Junction Temperature Range	T_J	-55 to 150	°C

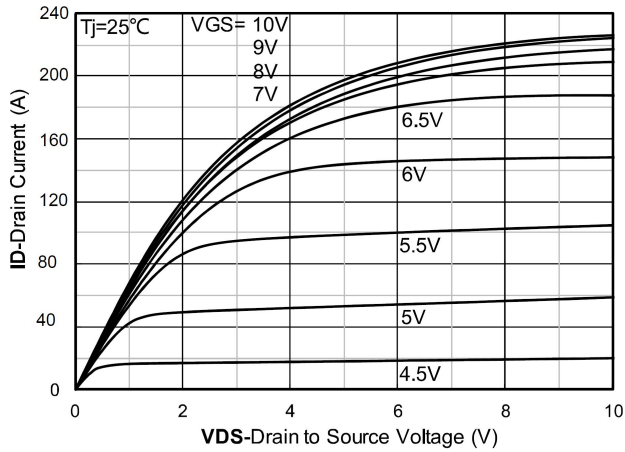
Electrical characteristics (Ta=25°C, unless otherwise noted)

Characteristics	Symbol	Test Condition	Min	Typ	Max	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	ID = 250μA, VGS = 0V	150	-	-	V
Drain Cut-Off Current	IDSS	VDS = 120V, VGS = 0V	-	-	1	μA
Gate Leakage Current	IGSS	VGS = ±20V, VDS = 0V	-	-	±100	nA
Gate Threshold Voltage	VGS(th)	VDS = VGS, ID = 250μA	2.0	3.0	4.0	V
Drain-Source ON Resistance	RDS(ON)	VGS = 10V, ID = 20A	-	5.2	6.5	mΩ
Dynamic Characteristics						
Input Capacitance	Ciss	VDS = 75V, VGS = 0V, f = 1.0MHz	-	5450	-	pF
Output Capacitance	Coss		-	690	-	
Reverse Transfer Capacitance	Crss		-	26	-	
Total Gate Charge	Qg	VDS = 75V, VGS = 10V, ID=20A	-	78	-	nC
Gate-Source Charge	Qgs		-	34	-	
Gate-Drain Charge	Qgd		-	22	-	
Switching Characteristics						
Turn-On Delay Time	td(on)	VGS = 10V, VDS = 75V, ID = 20A, RG = 3Ω	-	24	-	nS
Rise Time	tr		-	35	-	
Turn-Off Delay Time	td(off)		-	46	-	
Fall Time	tf		-	15	-	
Drain-Source Body Diode Characteristics						
Source-Drain Diode Forward Voltage	VSD	Is = 1A, VGS = 0V	-	-	1.2	V
Maximum Body-Diode Continuous Current	Is		-	-	185	A
Body Diode Reverse Recovery Time	Trr	Is = 15A, di/dt=100A/us, TJ=25℃	-	108	-	nS
Body Diode Reverse Recovery Charge	Qrr		-	312	-	nC

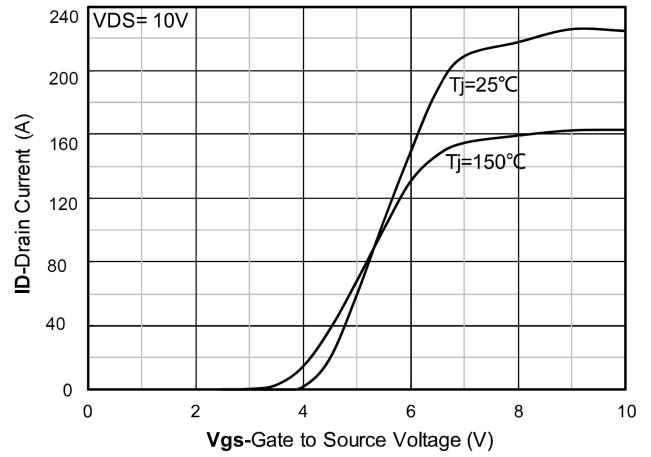
Note :

1. The test condition is $V_{DD} = 75V, V_{GS} = 10V, L = 0.5mH, RG = 25\Omega$;

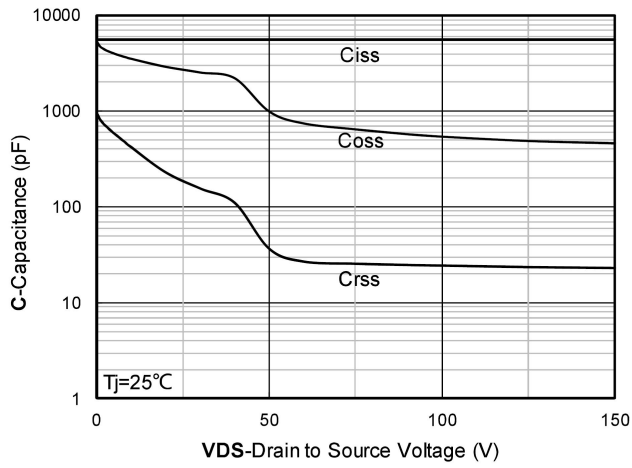
Typical Characteristics



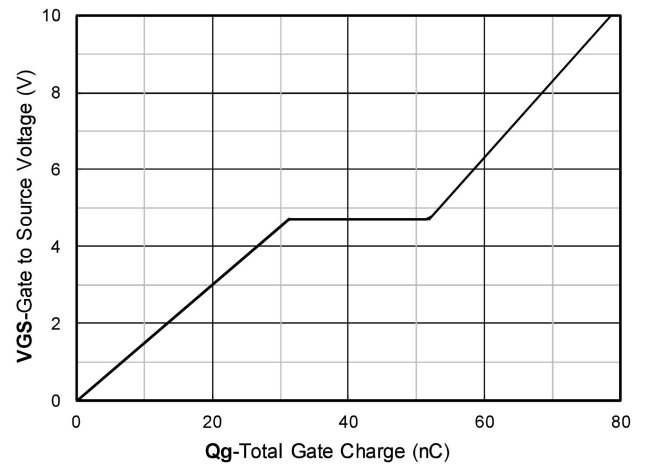
Output Characteristics typical values



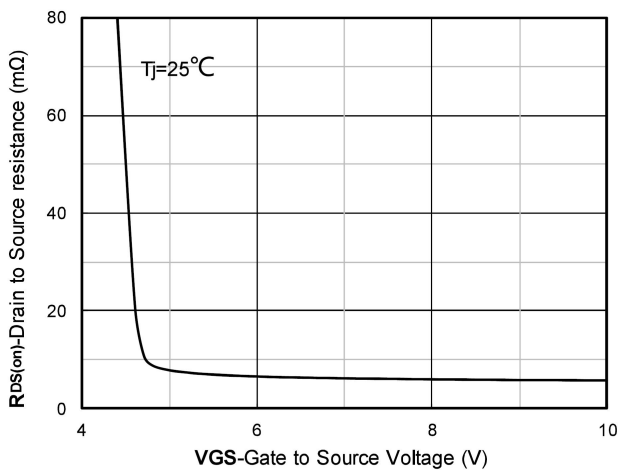
Transfer Characteristics typical values



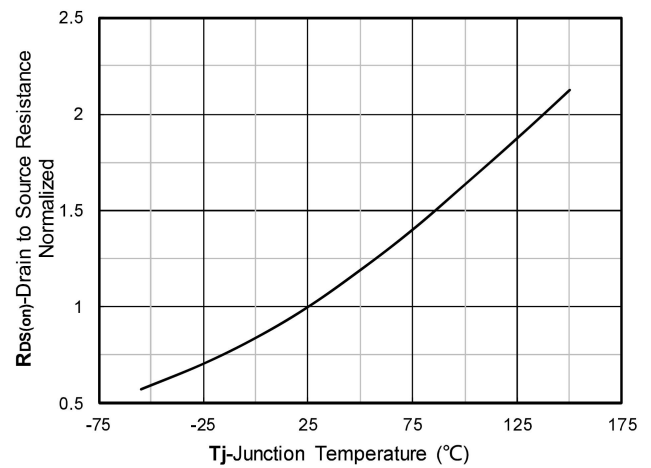
Capacitance Characteristics typical values



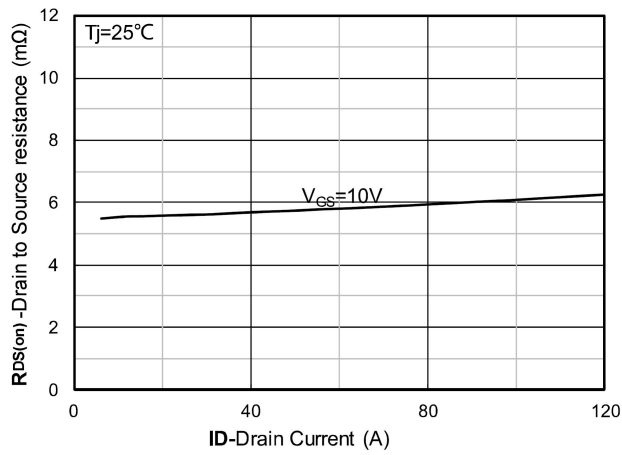
Gate Charge typical values



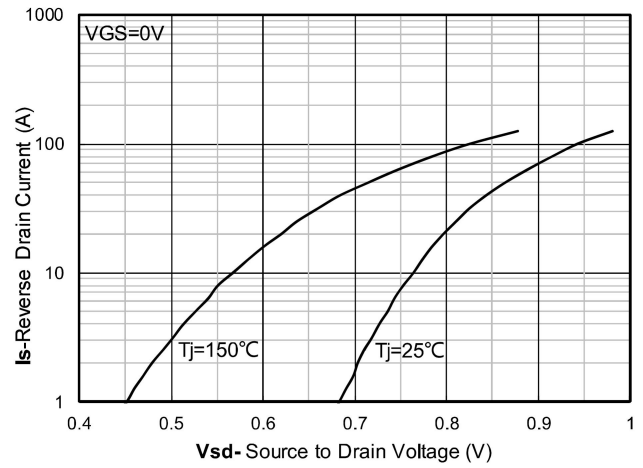
On-Resistance vs Gate to Source Voltage typical values



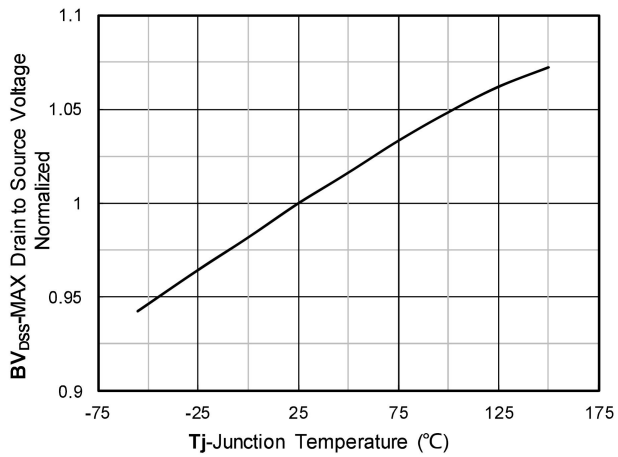
Normalized On-Resistance



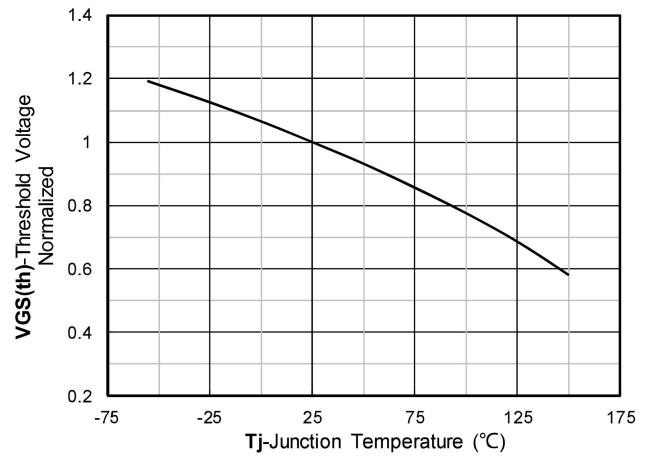
RDS(on) VS Drain Current typical values



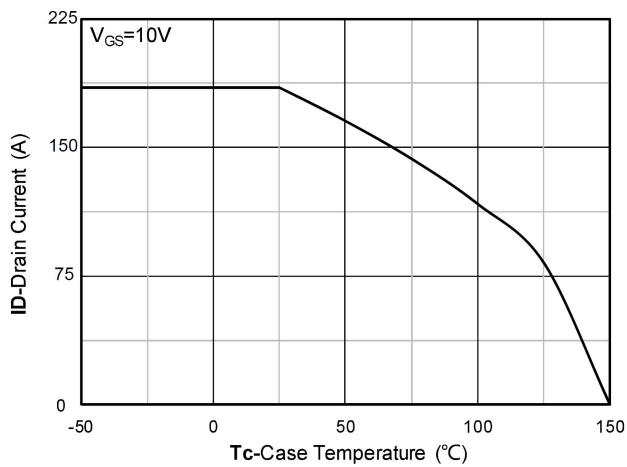
Forward characteristics of reverse diode typical values



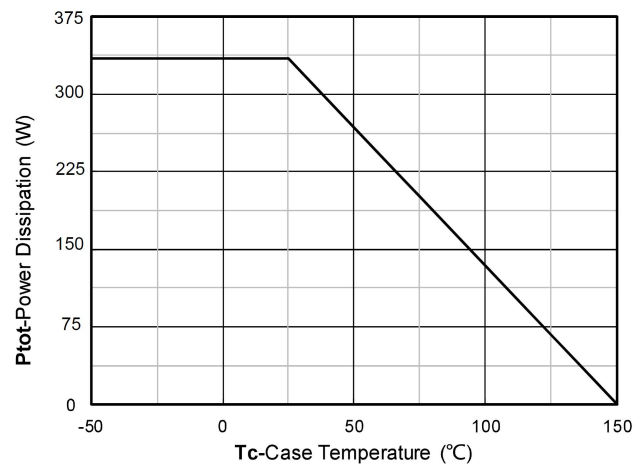
Normalized breakdown voltage



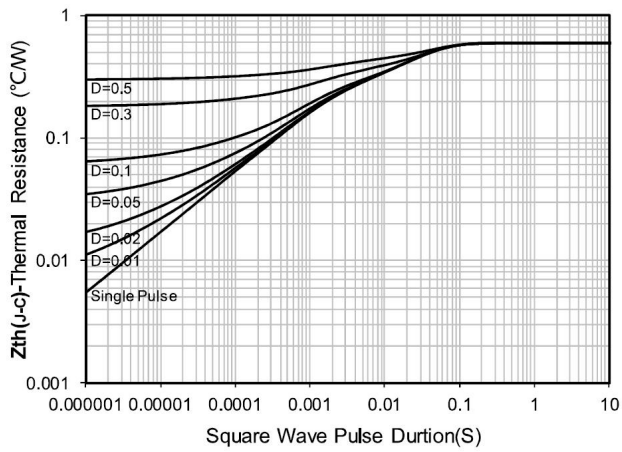
Normalized Threshold voltage



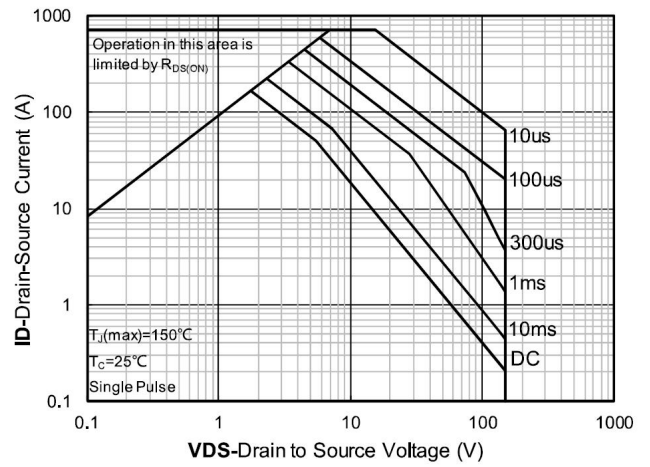
Current dissipation



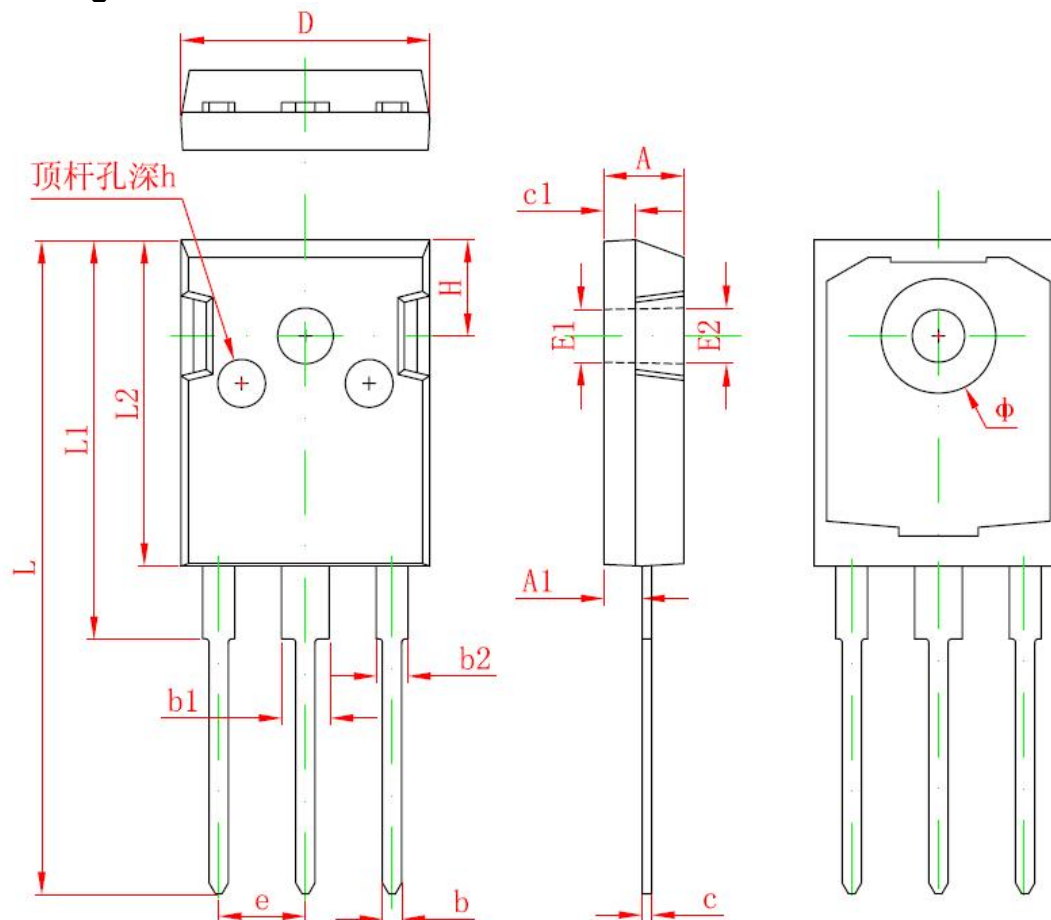
Power dissipation



Maximum Transient Thermal Impedance



Safe Operation Area

TO-247 Package Information


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	4.850	5.150	0.191	0.200
A1	2.200	2.600	0.087	0.102
b2	1.800	2.200	0.071	0.087
b	1.000	1.400	0.039	0.055
b1	2.800	3.200	0.110	0.126
c	0.500	0.700	0.020	0.028
c1	1.900	2.100	0.075	0.083
D	15.450	15.750	0.608	0.620
E1	3.500 REF.		0.138 REF.	
E2	3.600 REF.		0.142 REF.	
L	40.900	41.300	1.610	1.626
L1	24.800	25.100	0.976	0.988
L2	20.300	20.600	0.799	0.811
Φ	7.100	7.300	0.280	0.287
e	5.450 TYP.		0.215 TYP.	
H1	5.980 REF.		0.235 REF.	
h	0.000	0.300	0.000	0.012